### INTEGRATED CIRCUITS

# DATA SHEET



# TDA6508; TDA6508A; TDA6509; TDA6509A

3-band mixer/oscillator and PLL for terrestrial tuners

Product specification Supersedes data of 2005 Feb 23 2005 Mar 25





### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

CONTENT	-s	13	TEST AND APPLICATION INFORMATION
1 2 3 4	FEATURES APPLICATIONS GENERAL DESCRIPTION QUICK REFERENCE DATA	13.1 14 15 16 16.1	Measurement circuit INTERNAL PIN CONFIGURATION PACKAGE OUTLINES SOLDERING Introduction to soldering surface mount
5 6 7 8 8.1 8.2	ORDERING INFORMATION BLOCK DIAGRAM PINNING I <sup>2</sup> C-BUS DATA FORMAT I <sup>2</sup> C-bus address selection	16.2 16.3 16.4 16.5	packages Reflow soldering Wave soldering Manual soldering Suitability of surface mount IC packages for wave and reflow soldering methods
8.3 8.4	Write mode Read mode Power-on reset	17 18	DATA SHEET STATUS DEFINITIONS
9 10	LIMITING VALUES HANDLING THERMAN CHARACTERISTICS	19	DISCLAIMERS
11 12	THERMAL CHARACTERISTICS CHARACTERISTICS		

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

#### 1 FEATURES

- Single-chip 5 V mixer / oscillator and synthesizer for TV, VCR tuners, DVD-R and PC TV.
- I<sup>2</sup>C bus protocol compatible with 3.3 V and 5 V microcontrollers
  - Address with 4 data bytes transmission (I<sup>2</sup>C-bus 'write' mode)
  - Address with 1 status byte (I<sup>2</sup>C-bus 'read' mode)
  - 4 independent I<sup>2</sup>C-bus addresses.
- 5 Positive-channel Metal Oxide Semiconductor (PMOS) output ports
  - 3 buffers for band selection (20 mA)
  - 2 buffers for general purpose, e.g. FM sound trap (5 mA).
- 33 V tuning voltage output
- · In-lock flag
- 5-step analog-to-digital converter (3 bits in I<sup>2</sup>C-bus mode)
- 15-bit programmable divider
- Programmable reference divider ratio (64, 80 or 128)
- Programmable charge-pump current (20 or 100 μA)
- Balanced mixer with a common emitter input for LOW band (single input)
- Balanced mixer with a common emitter input for MID band (balanced input)
- Balanced mixer with a common base input for HIGH band (balanced input)
- · 2-pin asymmetrical oscillator for LOW band
- 2-pin symmetrical oscillator for MID band
- · 2-pin symmetrical oscillator for HIGH band
- External 4-pin IF filter between mixer output (medium impedance) and IF amplifier input (high impedance)
- Weak signal booster (I<sup>2</sup>C controlled switchable gain amplifier)
- Low power
- Low radiation
- Small size
- TDA6508; TDA6509: symmetrical IF amplifier output to drive a SAW filter (1.25 kΩ)
- TDA6508A; TDA6509A: single-ended IF amplifier to drive low ohmic load (75 Ω).



#### 2 APPLICATIONS

• 3-band tuner for terrestrial TV, DVD-R, VCR and PC TV.

#### 3 GENERAL DESCRIPTION

This device is a programmable 3-band mixer oscillator and synthesizer intended for LOW, MID and HIGH band TV and VCR tuners. It has three double balanced mixers and three oscillators for the LOW, MID and HIGH band respectively, a PLL synthesizer, and an IF amplifier. There are four package variants: TDA6508, TDA6509, TDA6508A and TDA6509A. Versions TDA6508; TDA6509 have a symmetrical IF amplifier; versions TDA6508A; TDA6509A have an asymmetrical IF amplifier, (see Fig.1).

The common output of all three mixers can be connected, via two output pins, to an external IF filter to enable shunted IF bandpass and/or serial filtering for improved signal handling. Two input pins are available for connecting the output of the external filter to the input of the IF amplifier. The mixer output has an impedance of 300  $\Omega$ . The IF amplifier input has an impedance of 2.5 k $\Omega$  (5 pF).

The overall gain of the tuner can be increased at low signal amplitude conditions to improve TV reception by activating a weak signal booster via the  $I^2C$ -bus.

There are five open-drain PMOS output ports; each port has a different drive capability. I<sup>2</sup>C-bus bit P0 enables port P0 (20 mA drain current) and the LOW band mixer oscillator. Bit P1 enables port P1 (20 mA drain current) and the MID band mixer oscillator. When ports P0 and P1 are both disabled, the HIGH band mixer oscillator is enabled. Bit P2 enables port P2 (20 mA drain current). Bit P3 enables port P3 (5 mA drain current) for general use, and bit P4 enables port P4 (5 mA drain current) for general use, and is also combined with the ADC input. When the ports are used, the sum of the drain currents must be limited to 30 mA.

The PLL synthesizer comprises a 15-bit programmable divider, a crystal oscillator, programmable reference divider, phase comparator (phase/frequency detector) combined with a charge-pump which drives an internal tuning amplifier and an output at pin CP. The CP signal current can be integrated by connecting an external RC

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

loop filter between pin CP and pin VTUNE as shown in Fig.27. The tuning amplifier can supply up to 33 V (max.) at pin VT for controlling any of the internal oscillators via external tank circuits. The phase comparator can operate at 62.5, 50 or 31.25 kHz with a 4 MHz crystal, depending on the reference divider ratio of either 64, 80 or 128; see Table 4. An externally sourced signal having a frequency between 3.58 MHz and 4.43 MHz can be used as a reference frequency for the internal crystal oscillator at any of the reference divider ratios.

In test mode, port P3 will output either half the crystal reference frequency ( $\frac{1}{2}f_{ref}$ ) or half the reference divider frequency ( $\frac{1}{2}f_{div}$ ); see Table 5.

The device can be controlled according to the I<sup>2</sup>C-bus format; see Table 1. The in-lock flag bit FL is set to logic 1 when the PLL is locked. This flag is read from the status byte on pin SDA during a READ operation; see Table 6 and Table 7.

Automatic frequency control is provided using an internal Analog-to-Digital Converter controlled by the voltage on pin ADC. The ADC code is read during a READ operation; see Table 8.

The device requires to be addressed by five sequential serial bytes (including the address byte) via the I<sup>2</sup>C-bus to set the crystal oscillator frequency, program the five ports and to set the charge-pump current; see Table 1. The address byte can have one of four possible device addresses which are selected by applying a specific voltage to pin AS; see Table 3.

#### 4 QUICK REFERENCE DATA

Measured over full voltage and temperature ranges.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>CC</sub>	supply voltage		4.5	5	5.5	V
I <sub>CC</sub>	supply current	V <sub>CC</sub> = 5 V; all ports off	43	58	74	mA
f <sub>xtal</sub>	crystal oscillator frequency	$R_{xtal} = 25 \Omega \text{ to } 300 \Omega$	3.58	4.0	4.43	MHz
P <sub>tot</sub>	total power dissipation		_	290	385	mW
T <sub>stg</sub>	IC storage temperature		-40	_	+150	°C
T <sub>amb</sub>	ambient temperature		-20	_	+85	°C

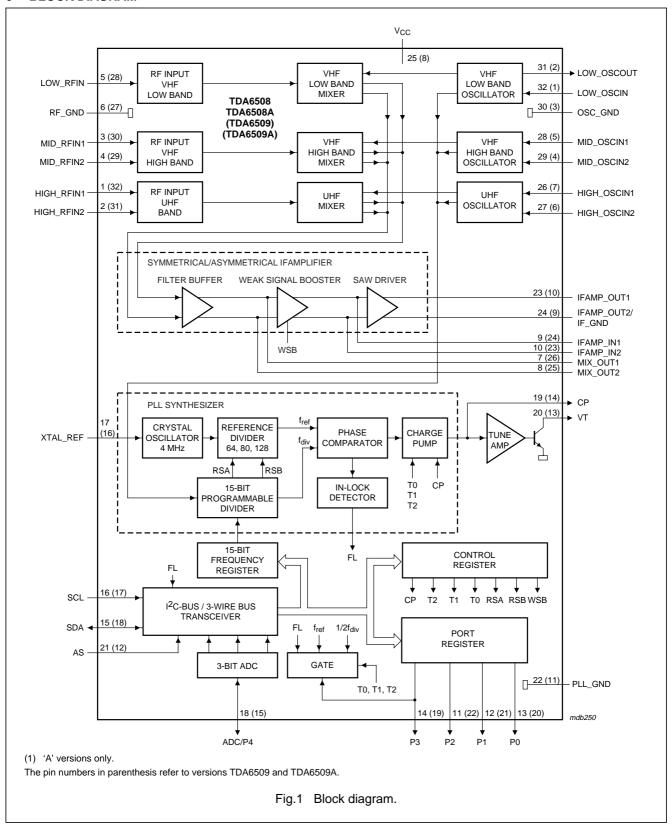
#### 5 ORDERING INFORMATION

TYPE		PACKAGE	
NUMBER	NAME	DESCRIPTION	VERSION
TDA6508TT	TSSOP32	plastic thin shrink small outline package; 32 leads body width 6.1 mm	SOT487-1
TDA6508ATT	1		
TDA6509TT	TSSOP32	plastic thin shrink small outline package; 32 leads body width 6.1 mm	SOT487-1
TDA6509ATT			
TDA6509HN	HVQFN32	plastic thermal enhanced very thin quad flat package; no leads;	SOT617-1
TDA6509AHN		32 terminals; body $5 \times 5 \times 0.85$ mm	

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509; TDA6509A

#### 6 BLOCK DIAGRAM



# 3-band mixer/oscillator and PLL for terrestrial tuners

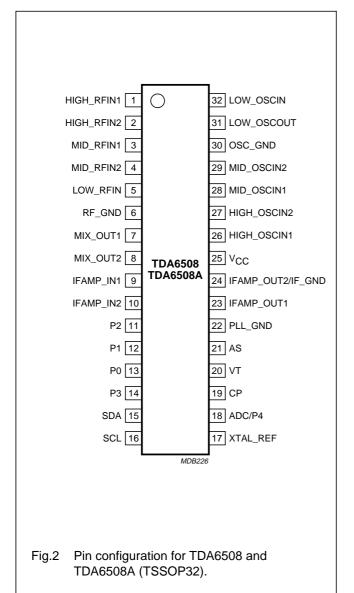
TDA6508; TDA6508A; TDA6509A

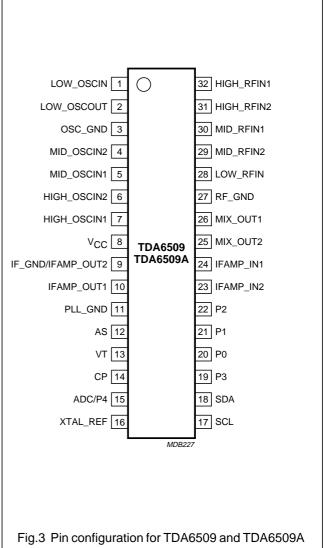
### 7 PINNING

	P	IN	
SYMBOL	TDA6508; TDA6508A	TDA6509; TDA6509A	DESCRIPTION
HIGH_RFIN1	1	32	HIGH band RF input 1
HIGH_RFIN2	2	31	HIGH band RF input 2
MID_RFIN1	3	30	MID band RF input 1
MID_RFIN2	4	29	MID band RF input 2
LOW_RFIN	5	28	LOW band RF input
RF_GND	6	27	RF ground
MIX_OUT1	7	26	mixer output 1 (to external IF filter)
MIX_OUT2	8	25	mixer IF output 2 (to external IF filter)
IFAMP_IN1	9	24	IF amplifier input 1 (from external IF filter)
IFAMP_IN2	10	23	IF amplifier input 2 (from external IF filter)
P2	11	22	HIGH band port output
P1	12	21	MID band port output
P0	13	20	LOW band port output
P3	14	19	general purpose port - test mode output
SDA	15	18	serial data input/output
SCL	16	17	serial clock input
XTAL_REF	17	16	crystal oscillator reference signal input
ADC/P4	18	15	ADC input/general purpose port output
СР	19	14	charge-pump output
VT	20	13	tuning voltage output
AS	21	12	address selection input
PLL_GND	22	11	PLL ground
IFAMP_OUT1	23	10	IF amplifier output 1
IFAMP_OUT2	24	9	IF amplifier output 2 (TDA6508 and TDA6509 only)
IF_GND	24	9	IF ground (TDA6508A and TDA6509A only)
V <sub>CC</sub>	25	8	supply voltage
HIGH_OSCIN1	26	7	HIGH band oscillator input 1
HIGH_OSCIN2	27	6	HIGH band oscillator input 2
MID_OSCIN1	28	5	MID band oscillator input 1
MID_OSCIN2	29	4	MID band oscillator input 2
OSC_GND	30	3	oscillator ground
LOW_OSCOUT	31	2	LOW band oscillator output
LOW_OSCIN	32	1	LOW band oscillator input

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509; TDA6509A



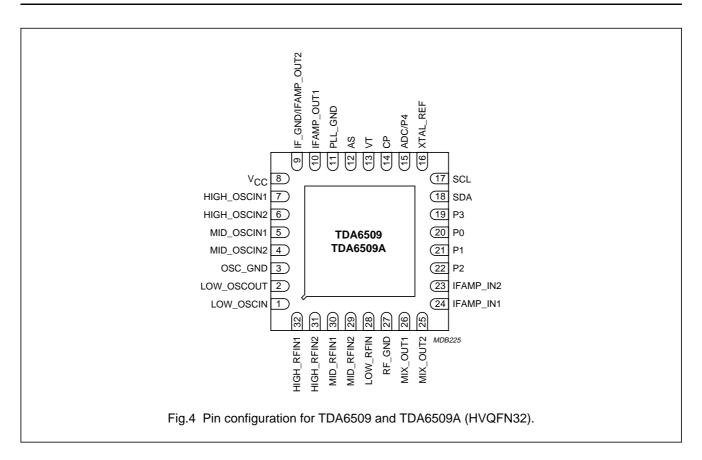


(TSSOP32).

2005 Mar 25 7

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A



#### 8 I2C-BUS DATA FORMAT

### 8.1 I<sup>2</sup>C-bus address selection

The address byte ADB contains programmable module address bits MA1 and MA0 which allow up to four synthesizers to be used in the same system, and are configured by applying one of four possible voltages on pin AS; see Tables 1 and 2. For each voltage on pin AS, the resultant values of bits MA1 and MA0 are shown in Table 3.

#### 8.2 Write mode

The write mode is defined by setting bit  $R/\overline{W}$  to logic 0 in address byte ADB; see Table 1.

Data bytes can be sent to the device after sending the first address byte. Four data bytes are required to fully program the device.

The bus transceiver has an auto-increment facility which allows the device to be programmed by one transmission (address byte with 4 data bytes). The device can be partially programmed provided that the first data byte following the address byte is divider byte DB1 or control byte CB.

The MSB of the first data byte DB1 indicates whether frequency data (MSB = 0) or control and band switch data will follow. Additional data bytes can be entered without the need to re-address the device until an  $I^2C$ -bus STOP command is sent by the controller.

The frequency divider register is loaded after the 8th clock pulse of byte DB2. The control register is loaded after the 8th clock pulse of byte CB, and the band switch register is loaded after the 8th clock pulse of byte BB.

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

**Table 1** I<sup>2</sup>C-bus data format for write mode

NAME	ВҮТЕ		BITS <sup>(1)</sup>						
NAME	BILE	MSB							LSB
Address byte	ADB	1	1	0	0	0	MA1	MA0	$R/\overline{W} = 0$
Divider byte 1	DB1	0	N14	N13	N12	N11	N10	N9	N8
Divider byte 2	DB2	N7	N6	N5	N4	N3	N2	N1	N0
Control byte	СВ	1	СР	T2	T1	T0	RSA	RSB	WSB
Band switch byte	BB	Х	Х	Х	P4	P3	P2	P1	P0

#### Note

1. X = don't care.

**Table 2** Function of write mode bits used in Table 1

BIT	FUNCTION			
MA1 and MA0	module address; see Table 3			
R/W	read/write mode; 0 = write mode			
N14 to N0	programmable divider bits: $N = N14 \times 2^{14} + N13 \times 2^{13} + + N1 \times 2^{1} + N0$			
СР	charge-pump current control:			
	0: charge-pump current is 20 μA			
	1: charge-pump current is 100 μA			
T2, T1 and T0	test mode; see Table 5			
RSA and RSB	reference divider ratio; see Table 4			
WSB	Weak Signal Booster control:			
	0: normal mode - no gain increase: external IF filter used			
	1: Weak Signal Booster activated: IF filter by-passed			
P0, P1, P2, P3, P4	port P0 to P4 control:			
	0: corresponding port is off; high impedance state (default)			
	1: corresponding port is on.			

Table 3 Module address selection bits

MA1	MA0	VOLTAGE APPLIED TO PIN AS			
0	0	0 V to 0.1V <sub>CC</sub>			
0	1	0.2V <sub>CC</sub> to 0.3V <sub>CC</sub> or open-circuit			
1	0	0.4V <sub>CC</sub> to 0.6V <sub>CC</sub>			
1	1	0.9V <sub>CC</sub> to 1.0V <sub>CC</sub>			

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509; TDA6509A

Table 4 Reference divider ratio selection bits

RSA	RSB	REFERENCE DIVIDER RATIO	FREQUENCY STEP (kHz)(1)
X	0	80	50
0	1	128	31.25
1	1	64	62.5

#### Note

1. Crystal oscillator frequency or externally sourced reference frequency of 4 MHz at pin XTAL\_REF.

Table 5 Test mode selection bits

T2	T1	ТО	TEST MODE	
0	0	0	normal mode (read and write mode bytes allowed)	
0	0	1	normal mode (read and write mode bytes allowed) <sup>(1)</sup>	
0	1	0	charge-pump is off <sup>(2)</sup>	
0	1	1	byte BB ignored	
1	1	0	charge-pump sinks current	
1	1	1	charge-pump sources current	
1	0	0	$^{1}\!/_{2}f_{\mathrm{ref}}$ is output from port P3 $^{(3)}$	
1	0	1	$\frac{1}{2}f_{\text{div}}$ is output from port P3 <sup>(3)</sup>	

#### **Notes**

- 1. This is the default mode at power-on reset.
- 2.  $\frac{1}{2}f_{div}$  is output from port P3 when the charge-pump is off.
- 3. Port P3 cannot be used when these test modes are active.

#### 8.3 Read mode

The read mode is defined by setting bit  $R/\overline{W}$  to logic 1 in address byte ADB; see Table 6.

After the slave address has been recognized, the device generates an acknowledge pulse, and status byte SB is transferred on the SDA line (MSB first). Data is valid on the SDA line when pin SCL is HIGH. A second data byte can be read from the device if the microcontroller generates an acknowledge on the SDA line (master acknowledge).

End of transmission will occur if no master acknowledge is asserted. The device will then release the data line to allow the microcontroller to generate a STOP condition.

Bit POR is set to logic 1 at power-on. This bit is reset when an end-of-data is detected by the device at the end of a read sequence. Bit FL controls the PLL by indicating when the loop is locked (bit FL = 1).

The internal ADC can be used to apply AFC information to a microcontroller in the IF section of the television via status byte bits A0, A1 and A2. Up to five voltage levels can be applied to the ADC input pin ADC; the resultant values of bits A2, A1 and A0 are shown in Table 8.

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

Table 6 Read data format

NAME	BYTE				В	IT			
NAME	BIIE	MSB <sup>(1)</sup>							LSB
Address byte	ADB	1	1	0	0	0	MA1	MA0	$R/\overline{W} = 1$
Status byte	SB	POR	FL	1	1	1	A2	A1	A0

#### Note

1. MSB is transmitted first.

Table 7 Description of the bits used in Table 6

BIT	DESCRIPTION			
MA1 and MA0	rogrammable address bits; see Table 3			
R/W	read/write mode selection; 1 = read mode			
POR	Power-on reset flag:			
	0: after end of the first read sequence			
	1: at Power-on			
FL	in-lock flag:			
	0: loop is not locked			
	1: loop is locked			
A2, A1 and A0	digital outputs of the 5-level ADC; see Table 8			

 Table 8
 Digital outputs for analog to digital converter (note 1)

A2	A1	A0	VOLTAGE APPLIED TO PIN ADC
0	0	0	0 V <sub>CC</sub> to 0.15 V <sub>CC</sub>
0	0	1	0.15 V <sub>CC</sub> to 0.3 V <sub>CC</sub>
0	1	0	0.3 V <sub>CC</sub> to 0.45 V <sub>CC</sub>
0	1	1	0.45 V <sub>CC</sub> to 0.6 V <sub>CC</sub>
1	0	0	0.6 V <sub>CC</sub> to 1 V <sub>CC</sub>

#### Note

1. Accuracy is  $\pm 0.03 \times V_{CC}$ .

#### 8.4 Power-on reset

The threshold level for the power-on reset supply voltage  $V_{POR}$  is set to 3.2 V at room temperature. Below this threshold, the device is reset to the power-on state.

The following actions take place In the power-on state:

- The charge-pump current is set to 100  $\mu A$
- Test bits T2, T1 and T0 are set to logic 001; the charge-pump can either sink or source current
- The Weak signal booster is disabled
- All ports are off and the HIGH band is selected by default.

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

Table 9 Default setting of the bits at power-on reset

NAME	DVTE		BITS <sup>(1)</sup>							
NAME	BYTE	MSB							LSB	
Address byte	ADB	1	1	0	0	0	MA1	MA0	Х	
Divider byte 1	DB1	0	Х	Х	Х	Х	Х	Х	Х	
Divider byte 2	DB2	Х	Х	Х	Х	Х	Х	Х	Х	
Control byte	СВ	1	1	0	0	1	Х	Х	0	
Band switch byte	BB	Х	Х	Х	0	0	0	0	0	

#### Note

1. X = don't care.

#### 9 LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); note 1.

	Р	IN				
SYMBOL	TDA6508; TDA6508A	TDA6509; TDA6509A	PARAMETER	MIN.	MAX.	UNIT
V <sub>CC</sub>	25	8	DC supply voltage	-0.3	+6	V
			operating supply	4.5	5.5	V
V <sub>Pn</sub>	11, 12, 13, 14, 18	22, 21, 20, 19, 15	PMOS port output voltage	-0.3	$V_{CC} + 0.3$	V
I <sub>Pn</sub>	11, 12, 13	22, 21, 20	PMOS port output current	-20	0	mA
	14, 18	19, 15		-5	0	mA
$V_{VT}$	20	13	tuning voltage output	-0.3	+35	V
V <sub>SCL</sub>	16	17	serial clock input voltage	-0.3	+6	V
V <sub>SDA</sub>	15	18	serial data input or output voltage	-0.3	+6	V
I <sub>SDA</sub>	15	18	serial data output current	0	+10	mA
V <sub>AS</sub>	21	12	address selection input voltage	-0.3	+6	V
$V_{xtal}$	17	16	crystal input voltage	-0.3	V <sub>CC</sub> + 0.3	V
t <sub>sc(max)</sub>	-	-	maximum short-circuit time (all pins to V <sub>CC</sub> and all pins to all grounds)	-	10	s
T <sub>stg</sub>	_	_	storage temperature	-40	+150	°C
T <sub>amb</sub>	_	_	ambient temperature	-20	+85	°C
Tj	_	_	junction temperature	-	+150	°C

#### Note

1. Maximum ratings can not be exceeded, not even momentarily without causing irreversible IC damage. Maximum ratings can not be accumulated.

### 10 HANDLING

Human Body Model: C = 100 pF and R = 1500  $\Omega$ . All pins withstand 2000 V in accordance with specification *EIA/JESD22-A114-A*.

Machine model: C = 200 pF and  $R = 0 \Omega$ . All pins withstand 200 V in accordance with specification *EIA/JESD22-A115-A*.

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

#### 11 THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	TYP.	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air - SOT487-5 <sup>(1)</sup>	115	K/W
		in free air - SOT487-4 <sup>(1)</sup>	125	K/W
		in free air - SOT617-1	31	K/W

#### Note

1. JEDEC conditions apply to single layer PCB.

#### 12 CHARACTERISTICS

 $V_{CC}$  = 5 V,  $T_{amb}$  = 25 °C; TDA6508 and TDA6509 values measured with  $R_L$  = 1.25 k $\Omega$  and TDA6508A and TDA6509A values measured with  $R_L$  = 75  $\Omega$ ; Weak signal booster off; measured using the PAL application circuit shown in Figure 27; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply	1		!	!	•	
V <sub>CC</sub>	supply voltage		4.5	5.0	5.5	V
I <sub>CC</sub>	supply current	at V <sub>CC</sub> = 5 V; all ports off	43	58	74	mA
FUNCTIONAL	RANGE			•	•	-
V <sub>POR</sub>	power-on reset supply voltage	power-on reset activates below this voltage	_	3.2	_	V
N	divider ratio	15-bit frequency word	64	_	32767	_
f <sub>xtal</sub>	crystal oscillator frequency	$R_{xtal} = 25 \Omega \text{ to } 300 \Omega$	3.58	4.0	4.43	MHz
Z <sub>xtal</sub>	input impedance (absolute value)	f <sub>xtal</sub> = 4 MHz	1000	1200	_	Ω
PMOS POR	TS: PINS P0, P1, P2, P3, P4		•		•	
I <sub>L(Pn)</sub>	leakage current	V <sub>CC</sub> = 5.5 V; V <sub>Pn</sub> = 0 V or 5.5 V	-10	_	+120	μΑ
V <sub>Pn(sat)</sub>	output saturation voltage	$V_{Pn(sat)} = V_{CC} - V_{Pn}$				
		one buffer output is on and sourcing 5 mA	_	0.25	0.4	V
		one buffer output is on and sourcing 20 mA	_	0.25	0.4	V
ADC INPUT:	PIN ADC (IN I <sup>2</sup> C BUS MODE)		•			
V <sub>ADC</sub>	ADC input voltage	see Table 8	0	_	V <sub>CC</sub>	V
I <sub>ADC(H)</sub>	HIGH level input current	$V_{ADC} = V_{CC}$	_	-	100	μΑ
I <sub>ADC(L)</sub>	LOW level input current	V <sub>ADC</sub> = 0 V	-10	-	-	μΑ
ADDRESS SE	LECTION INPUT: PIN AS					
I <sub>AS(H)</sub>	HIGH level input current	V <sub>AS</sub> = 5 V	_	_	10	μΑ
I <sub>AS(L)</sub>	LOW level input current	V <sub>AS</sub> = 0 V	-10	_	_	μΑ

# 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
CLOCK AND	DATA INPUTS: PINS SCL AND SDA	A	•			
V <sub>SCL(L)</sub> , V <sub>SDA(L)</sub>	LOW level input voltage		0	_	1.5	V
V <sub>SCL(H)</sub> , V <sub>SDA(H)</sub>	HIGH level input voltage		2.3	-	5.5	V
I <sub>SCL(H)</sub> ,	HIGH level input current	V <sub>bus</sub> = 5.5 V; V <sub>CC</sub> = 0 V	_	_	10	μΑ
I <sub>SDA(H)</sub>		$V_{bus} = 5.5 \text{ V}; V_{CC} = 5.5 \text{ V}$	_	_	10	μΑ
$I_{SCL(L)}$ ,	LOW level input current	$V_{bus} = 1.5 \text{ V}; V_{CC} = 0 \text{ V}$	_	_	10	μΑ
I <sub>SDA(L)</sub>		$V_{bus} = 0 \text{ V}; V_{CC} = 5.5 \text{ V}$	-10	_	_	μΑ
DATA OUTPU	T: PIN SDA					
I <sub>L(SDA)</sub>	leakage current	V <sub>SDA</sub> = 5.5 V	<u> </u>	_	10	μΑ
V <sub>SDA(H)</sub>	HIGH level output voltage	I <sub>SDA</sub> = 3 mA (sink current)	_	_	0.4	V
CLOCK FREC	QUENCY (I <sup>2</sup> C-BUS MODE)					
f <sub>clk</sub>	clock frequency		_	_	400	kHz
CHARGE-PU	MP OUTPUT: PIN CP		•		•	•
I <sub>CP(H)</sub>	HIGH level input current (absolute value)	CP = 1	_	100	115	μΑ
I <sub>CP(L)</sub>	LOW level input current (absolute value)	CP = 0	15	20	-	μΑ
I <sub>L(CP)</sub>	off-state leakage current	T2 = 0; T1 = 1; T0 = 0	-15	0	+15	nA
TUNING VOLT	TAGE OUTPUT: PIN VT		•	•	•	
I <sub>tune(off)</sub>	leakage current when switched-off	T2 = 1; T1 = 1; T0 = 0; tuning supply is 33 V	_	-	10	μΑ
V <sub>o(tune)</sub>	output voltage when loop is closed	$T2 = 0$ ; $T1 = 0$ ; $T0 = 1$ ; $R_L = 33 kΩ$ ; tuning supply is 33 V	0.3	_	32.7	V
LOW MIXER	(INCLUDING IF PREAMPLIFIER)		•		•	•
f <sub>RF(o)</sub>	RF operational frequency		40	_	800	MHz
f <sub>RF</sub>	RF frequency	f <sub>pc</sub> ; note 1	43.25	_	161.25	MHz
G <sub>v</sub>	voltage gain	TDA6508; TDA6509; IF output loaded with 1.25 kΩ				
		f <sub>RF</sub> = 46 MHz; see Fig.10	22	25	28	dB
		f <sub>RF</sub> = 164 MHz; see Fig.10	22	25	28	dB
		TDA6508A; TDA6509A; IF output loaded with 75 $\Omega$				
		f <sub>RF</sub> = 46 MHz; see Fig.11	18	21	24	dB
		f <sub>RF</sub> = 164 MHz; see Fig.11	18	21	24	dB
NF	noise figure	f <sub>RF</sub> = 50 MHz; see Figs 12 and 13	_	8	10	dB
		f <sub>RF</sub> = 150 MHz; see Fig.13	-	8	10	dB

# 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>o</sub>	output voltage (causing 1%	TDA6508; TDA6509				
	cross-modulation in channel)	f <sub>RF</sub> = 43.25 MHz; see Fig.15	114	117	_	dΒμV
		f <sub>RF</sub> = 161.25 MHz; see Fig.15	114	117	_	dΒμV
		TDA6508A; TDA6509A				
		f <sub>RF</sub> = 43.25 MHz; see Fig.16	106	109	_	dΒμV
		f <sub>RF</sub> = 161.25 MHz; see Fig.16	106	109	_	dΒμV
V <sub>i</sub>	input voltage (causing pulling in channel at 750 Hz)	f <sub>RF</sub> = 161.25 MHz; note 2	_	90	_	dBμV
g <sub>os</sub>	optimum source conductance for noise figure	f <sub>RF</sub> = 50 MHz	_	0.7	_	mS
g <sub>i</sub>	input conductance	f <sub>RF</sub> = 43.25 MHz; see Fig.5	_	0.3	-	mS
		f <sub>RF</sub> = 161.25 MHz; see Fig.5	_	0.3	1-	mS
C <sub>i</sub>	input capacitance	$f_{RF} = 43.25 \text{ to } 161.25 \text{ MHz};$ see Fig.5	_	1	_	pF
LOW OSCILL	ATOR					
f <sub>osc(o)</sub>	oscillator operational frequency		60	_	600	MHz
f <sub>osc</sub>	oscillator frequency	note 3	82.15	_	200.15	MHz
$\Delta f_{OSC(V)}$	oscillator frequency variation	$\Delta V_{CC}$ = 5%; note 4	_	20	_	kHz
	with supply voltage	$\Delta V_{CC}$ = 10%; note 4	_	50	-	kHz
$\Delta f_{OSC(T)}$	oscillator frequency variation with temperature	$\Delta T = \pm 25$ °C; with compensation; note 5	_	900	_	kHz
		$\Delta T = 35$ °C; without compensation; note 5	_	1700	_	kHz
$\Phi_{\sf osc}$	phase noise, carrier-to-noise	worst case in the frequency range				
	sideband	±100 kHz frequency offset	_	-110	-107	dBc/Hz
		±10 kHz frequency offset	_	-90	-87	dBc/Hz
RSC <sub>(p-p)</sub>	ripple susceptibility of V <sub>CC</sub> (peak-to-peak value)	4.75 V <v<sub>CC &lt;5.25 V; worst case in the frequency range; ripple frequency 500 kHz; note 6</v<sub>	15	90	-	mV
$FM_mod$	FM modulation caused by I <sup>2</sup> C communication	worst case; note 7	_	_	2.12	kHz
MID MIXER (	INCLUDING IF PREAMPLIFIER)		,		•	
f <sub>O(RF)</sub>	RF operational frequency		40	_	800	MHz
f <sub>RF</sub>	RF frequency	f <sub>pc</sub> ; note 1	154.25	_	447.25	MHz

# 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
G <sub>v</sub>	voltage gain	TDA6508; TDA6509; IF output loaded with 1.25 kΩ				
		f <sub>RF</sub> = 157 MHz; see Fig.17	22	25	28	dB
		f <sub>RF</sub> = 450 MHz; see Fig.17	22	25	28	dB
		TDA6508A; TDA6509A; IF output loaded with 75 $\Omega$				
		f <sub>RF</sub> = 157 MHz; see Fig.18	18	21	24	dB
		f <sub>RF</sub> = 450 MHz; see Fig.18	18	21	24	dB
NF	noise figure	f <sub>RF</sub> = 150 MHz; see Figs 12 and 13	_	8	10	dB
		f <sub>RF</sub> = 300 MHz; see Figs 12 and 13	_	8	10	dB
V <sub>o</sub>	output voltage (causing 1%	TDA6508; TDA6509				
	cross-modulation in channel)	f <sub>RF</sub> = 154.25 MHz; see Fig.19	114	117	_	dΒμV
		f <sub>RF</sub> = 447.25 MHz; see Fig.19	114	117	_	dΒμV
		TDA6508; TDA6509A				
		f <sub>RF</sub> = 154.25 MHz; see Fig.20	106	109	_	dΒμV
		f <sub>RF</sub> = 447.25 MHz; see Fig.20	106	109	_	dBμV
V <sub>i</sub>	input voltage (causing pulling in channel at 750 Hz)	f <sub>RF</sub> = 447.25 MHz; note 2	_	90	_	dBμV
g <sub>os</sub>	optimum source	f <sub>RF</sub> = 150 MHz	_	0.9	_	mS
	conductance for noise figure	f <sub>RF</sub> = 300 MHz	-	1.5	_	mS
g <sub>i</sub>	input conductance	f <sub>RF</sub> = 154.25 MHz	_	0.21	_	mS
		f <sub>RF</sub> = 447.25 MHz	_	1.8	_	mS
C <sub>i</sub>	input capacitance	f <sub>RF</sub> = 154.25 to 447.25 MHz	_	0.6	-	pF
MID oscill	ATOR				•	'
f <sub>osc(o)</sub>	oscillator operational frequency		60		600	MHz
f <sub>osc</sub>	oscillator frequency	note 3	193.15	_	486.15	MHz
$\Delta f_{OSC(V)}$	oscillator frequency variation	$\Delta V_{CC}$ = 5%; note 4	_	15	_	kHz
( )	with supply voltage	$\Delta V_{CC}$ = 10%; note 4	_	40	_	kHz
$\Delta f_{OSC(T)}$	oscillator frequency variation with temperature	$\Delta T = \pm 25$ °C; with compensation; note 5	_	1200	_	kHz
		$\Delta T = 35$ °C; without compensation; note 5	_	2000	_	kHz
$\Phi_{ extsf{osc}}$	phase noise, carrier-to-noise	worst case in the frequency range				
	sideband	±100 kHz frequency offset	_	-109	-106	dBc/Hz
		±10 kHz frequency offset	_	-87	-86	dBc/Hz
RSC <sub>(p-p)</sub>	ripple susceptibility of V <sub>CC</sub> (peak-to-peak value)	4.75 V <v<sub>CC &lt;5.25 V; worst case in the frequency range; ripple frequency 500 kHz; note 6</v<sub>	15	70	-	mV
FM <sub>mod</sub>	FM modulation caused by I <sup>2</sup> C communication	worst case; note 7	_	_	2.12	kHz

# 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
HIGH MIXER	(INCLUDING IF PREAMPLIFIER)			'	•	'
f <sub>O(RF)</sub>	RF operational frequency		200		900	MHz
f <sub>RF</sub>	RF frequency	f <sub>pc</sub> ; note 1	439.25	_	863.25	MHz
G <sub>v</sub>	voltage gain	TDA6508; TDA6509; IF output loaded with 1.25 kΩ				
		f <sub>RF</sub> = 442 MHz; see Fig.21	33	36	39	dB
		f <sub>RF</sub> = 866 MHz; see Fig.21	33	36	39	dB
		TDA6508A; TDA6509A; IF output loaded with 75 $\Omega$				
		f <sub>RF</sub> = 442 MHz; see Fig.22	29	32	35	dB
		f <sub>RF</sub> = 866 MHz; see Fig.22	29	32	35	dB
NF n	noise figure (not corrected	f <sub>RF</sub> = 439.25 MHz; see Fig.23	_	7	9	dB
	for image)	f <sub>RF</sub> = 863.25 MHz; see Fig.23	_	7	9	dB
Vo	output voltage (causing 1%	TDA6508; TDA6509				
	cross-modulation in channel)	f <sub>RF</sub> = 439.25 MHz; Fig.25	114	117	_	dΒμV
		f <sub>RF</sub> = 863.25 MHz; Fig.25	114	117	_	dBμV
		TDA6508A; TDA6509A				
		f <sub>RF</sub> = 439.25 MHz; Fig.26	106	109	_	dΒμV
		f <sub>RF</sub> = 863.25 MHz; Fig.26	106	109	_	dBμV
Vi	input voltage (causing pulling in channel at 750 Hz)	f <sub>RF</sub> = 863.25 MHz; note 2	-	75	_	dBμV
Z <sub>i</sub>	input impedance (R <sub>S</sub> + jωL <sub>S</sub> )	R <sub>S</sub> at f <sub>RF</sub> = 439.25 MHz	_	28	_	Ω
		R <sub>S</sub> at f <sub>RF</sub> = 863.25 MHz	_	34	_	Ω
		L <sub>S</sub> at f <sub>RF</sub> = 439.25 MHz	_	8	_	nH
		L <sub>S</sub> at f <sub>RF</sub> = 863.25 MHz	_	8	_	nH
HIGH OSCILL	_ATOR		1			
f <sub>osc(o)</sub>	oscillator operational frequency		300		1000	MHz
f <sub>osc</sub>	oscillator frequency	note 3	478.15	_	902.15	MHz
$\Delta f_{OSC(V)}$	oscillator frequency variation	$\Delta V_{CC}$ = 5%; note 4	_	40	_	kHz
,	with supply voltage	$\Delta V_{CC}$ = 10%; note 4	_	80	_	kHz
$\Delta f_{OSC(T)}$	oscillator frequency variation with temperature	$\Delta T = \pm 25$ °C; with compensation; note 5	_	2700	-	kHz
		$\Delta T = 35$ °C; without compensation; note 5	_	4100	_	kHz
$\Phi_{ exttt{osc}}$	phase noise, carrier-to-noise	worst case in the frequency range				
	sideband	±100 kHz frequency offset	_	-105	-102	dBc/Hz
		±10 kHz frequency offset	_	-85	-82	dBc/Hz
RSC <sub>(p-p)</sub>	ripple susceptibility of V <sub>CC</sub> (peak-to-peak value)	4.75 V <v<sub>CC &lt;5.25 V; worst case in the frequency range; ripple frequency 500 kHz; note 6</v<sub>	15	50	_	mV

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$FM_{mod}$	FM modulation caused by I <sup>2</sup> C communication	worst case; note 7	-	_	3.0	kHz
WEAK SIGNA	L BOOSTER			•	•	
$\Delta G_{v(WSB)}$	gain increase when the weak signal booster mode is	TDA6508; TDA6509; IF = 36.15 MHz	13	16	_	dB
	activated	TDA6508A; TDA6509A; IF = 36.15 MHz	7	10	_	dB
IF PREAMPLIE	FIER		•	'	•	•
f <sub>O(IF)</sub>	IF operational frequency		5		60	MHz
Z <sub>o</sub>	output impedance	TDA6508; TDA6509				
	$(R_S + j\omega L_S)$	R <sub>S</sub> at 36.15 MHz	_	100	_	Ω
		L <sub>S</sub> at 36.15 MHz	_	52	_	nH
		TDA6508A; TDA6509A				
		R <sub>S</sub> at 36.15 MHz	_	40	_	Ω
		L <sub>S</sub> at 36.15 MHz	_	12	_	nH
REJECTION A	T THE IF OUTPUT		•	•	•	•
INT <sub>div</sub>	level of divider interferences in the IF signal	worst case; note 8	_	24	_	dBμV
IR <sub>xtal</sub>	crystal oscillator interferences rejection	worst case in the frequency range; note 9	60	80	_	dBc
R <sub>ref</sub>	reference frequency rejection	worst case in the frequency range; f <sub>ref</sub> = 62.5 kHz; note 10	60	66	_	dBc
INT <sub>SO2</sub>	channel SO2 beat	$V_{pc} = 80 \text{ dB}\mu\text{V}$ ; note 11	60	66	_	dBc

#### **Notes**

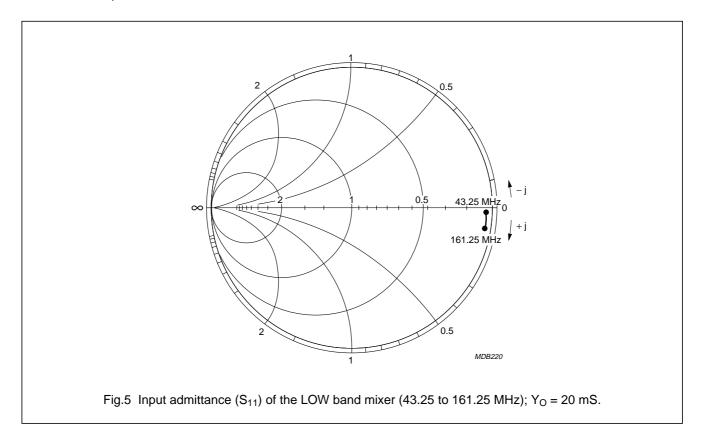
- 1. The range of  $f_{RF}$  is defined by the range of  $f_{osc}$  and I;  $f_{pc}$  = picture carrier frequency.
- 2. V<sub>i</sub> is the level of f<sub>RF</sub> (100% amplitude modulated with 11.89 kHz) that causes the frequency of the oscillator signal to deviate by 750 Hz; it produces sidebands 30 dB below the level of the oscillator signal.
- 3. Limits are related to the tank circuits used in Fig.27; frequency bands may be adjusted by the choice of external components.
- 4. The oscillator frequency shift is defined as a change in oscillator frequency when the supply voltage varies from  $V_{CC} = 5 \text{ V}$  to 4.75 V (or 5 V to 4.5 V) or from  $V_{CC} = 5 \text{ V}$  to 5.25 V (or 5 V to 5.5 V). The oscillator is free running during this measurement.
- 5. The oscillator frequency drift is defined as a change in oscillator frequency when the ambient temperature varies from  $T_{amb} = 25$  °C to 50 °C (60 °C max.) or from  $T_{amb} = 25$  °C to 0 °C. The oscillator is free running during this measurement. For  $\Delta T = \pm 25$  °C measurements, the tank circuit has temperature compensated values; for  $\Delta T = 35$  °C measurements, the tank circuit has non-temperature compensated values.
- 6. The ripple susceptibility is measured with a 500 kHz ripple signal applied to the supply voltage. The level of the ripple signal is increased until a difference of 53.5 dB occurs between the level of the IF carrier, fixed at 110 dB $\mu$ V for TDA6508; TDA6509 or 100 dB $\mu$ V for TDA6508A; TDA6509A, and the sideband components.
- 7. FM modulation of the local oscillator resulting from I<sup>2</sup>C-bus communication is measured at the IF output using a modulation analyzer with a peak-to-peak detector and a post detection filter of 20 Hz to 100 kHz. I<sup>2</sup>C-bus messages sent to the tuner address the tuner without changing the contents of the PLL registers. The maximum I<sup>2</sup>C-bus clock rate is 400 kHz. The I<sup>2</sup>C-bus pull-up resistor values are 1.5 kΩ.

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509; TDA6509A

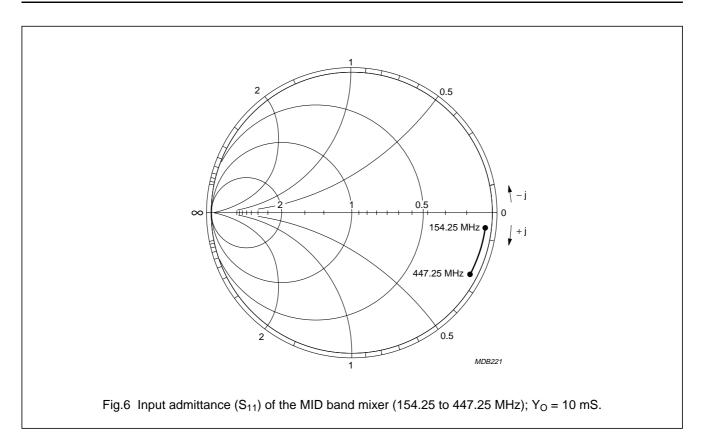
8. This is the level of signals close to the IF frequency which can interfere with the dividers. Typical interference signals are channel S3:  $f_{osc} = 256.15$  MHz,  $f_{osc} = 40.02$  MHz. The LOW and MID RF inputs must not be connected to any load or cable; the HIGH RF inputs are connected to a hybrid (balun).

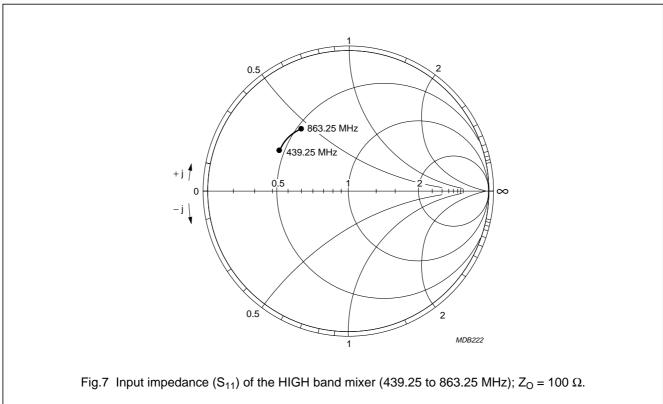
- Crystal oscillator interference is the 4 MHz sidebands produced by the crystal oscillator. The rejection must be greater than 60 dB for an IF output signal of 110 dB<sub>μ</sub>V for versions TDA6508; TDA6509 or 100 dB<sub>μ</sub>V for versions TDA6508A; TDA6509A.
- 10. Reference frequency rejection measures the level of reference frequency sidebands with respect to the sound sub-carrier f<sub>ssc</sub>.
- 11. Channel SO2 beat is the interfering product of the picture carrier frequency  $f_{pc}$ ,  $f_{IF}$  and  $f_{OSC}$  in channel SO2:  $f_{BEAT} = f_{osc} 2 \times f_{IF} = 37.35$  MHz. Another possible mechanism is:  $2 \times f_{pc} f_{osc}$ . For the measurement,  $V_{RF} = 80$  dB $\mu$ V.



### 3-band mixer/oscillator and PLL for terrestrial tuners

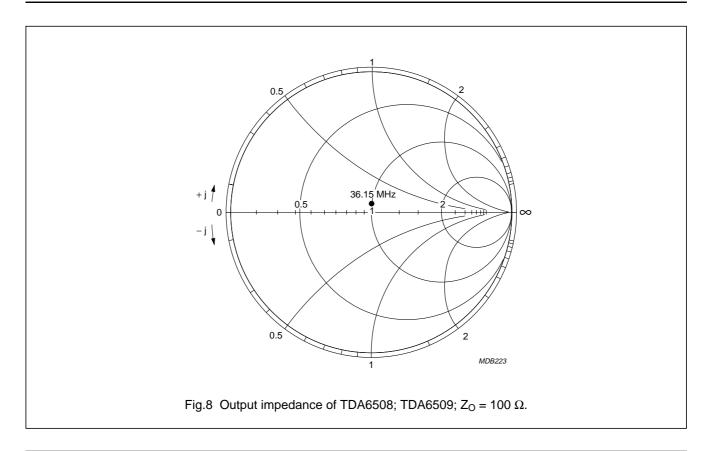
TDA6508; TDA6508A; TDA6509A

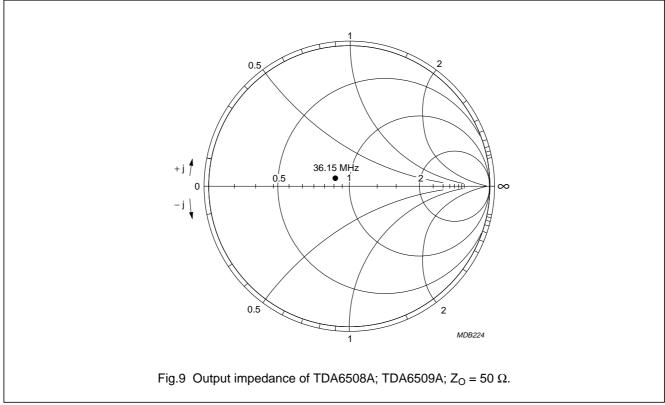




### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

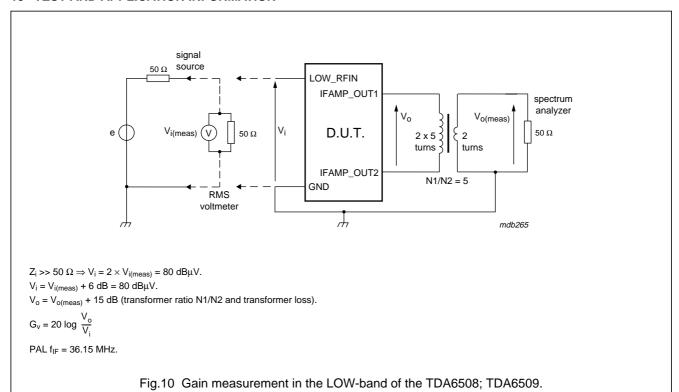


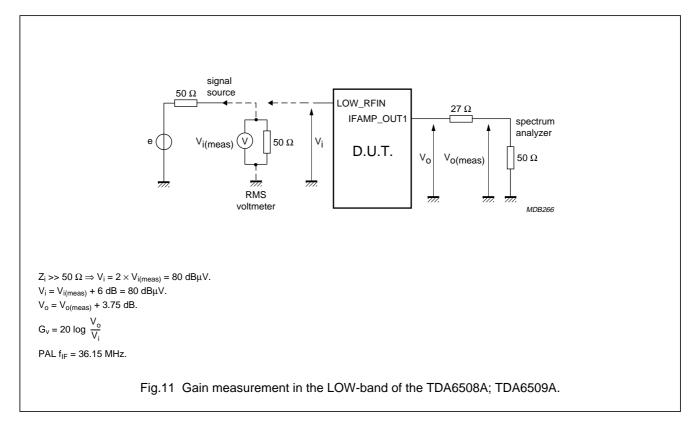


### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509; TDA6509A

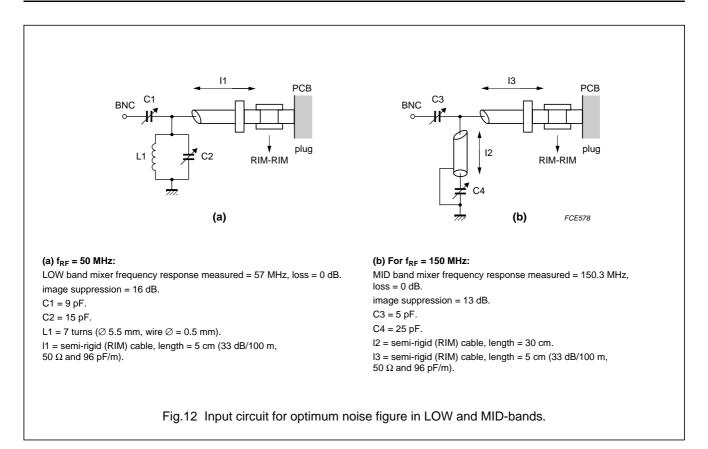
#### 13 TEST AND APPLICATION INFORMATION

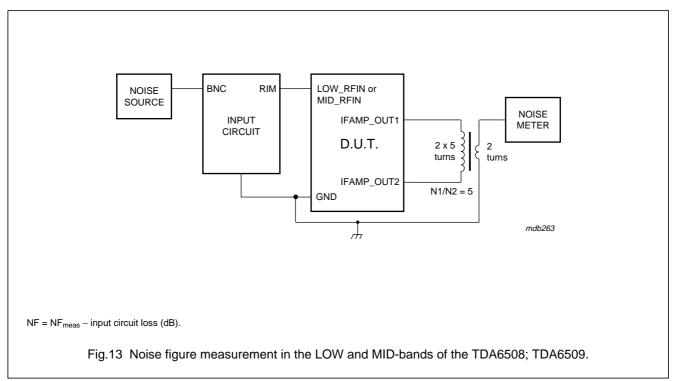




### 3-band mixer/oscillator and PLL for terrestrial tuners

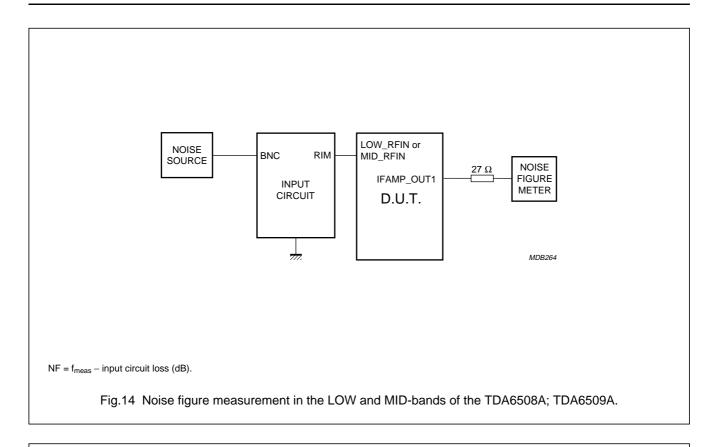
TDA6508; TDA6508A; TDA6509A

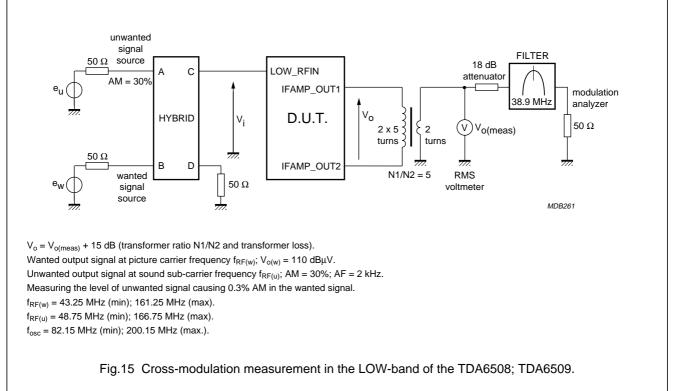




### 3-band mixer/oscillator and PLL for terrestrial tuners

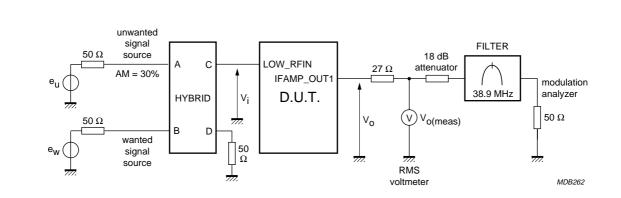
TDA6508; TDA6508A; TDA6509A





### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509; TDA6509A



 $V_o$  =  $V_{o(meas)}$  + 3.75 dB (transformer ratio N1/N2 and transformer loss).

Wanted output signal at picture carrier frequency  $f_{RF(w)}$ ;  $V_{o(w)} = 100 \text{ dB}\mu\text{V}$ .

Unwanted output signal at sound sub-carrier frequency  $f_{RF(u)}$ ; AM = 30%; AF = 2 kHz.

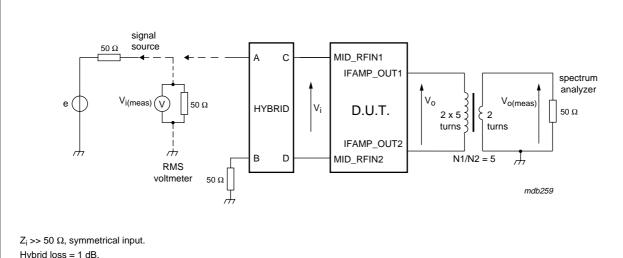
Measuring the level of unwanted signal causing 0.3% AM in the wanted signal.

 $f_{RF(w)} = 43.25 \text{ MHz (min.)}; 161.25 \text{ MHz (max.)}.$ 

 $f_{RF(u)} = 48.75 \text{ MHz (min.)}; 166.75 \text{ MHz (max.)}.$ 

 $f_{OSC} = 82.15 \text{ MHz (min.)}; 200.15 \text{ MHz (max.)}.$ 

Fig.16 Cross-modulation measurement in the LOW-band of the TDA6508A; TDA6509A.



 $V_i = V_{i(meas)} - loss + 6 + 3 = 80 dB\mu V.$ 

V<sub>o</sub> = V<sub>o(meas)</sub> + 15 dB (transformer ratio N1/N2 and transformer loss).

 $G_v = 20 \log \frac{v_0}{V_0}$ 

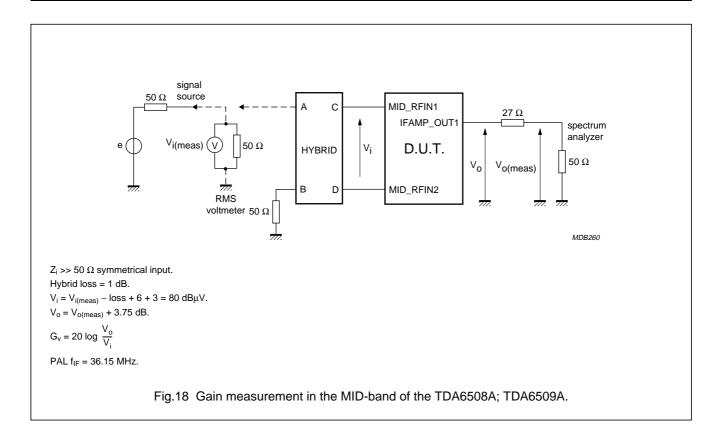
PAL f<sub>IF</sub> = 36.15 MHz.

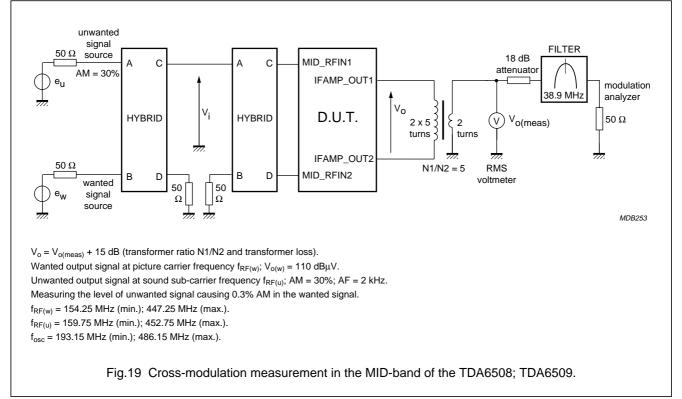
Fig.17 Gain measurement in the MID-band of the TDA6508; TDA6509.

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### 3-band mixer/oscillator and PLL for terrestrial tuners

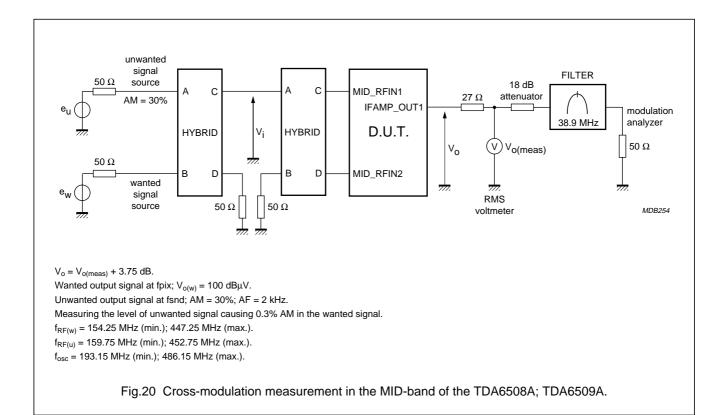
TDA6508; TDA6508A; TDA6509A

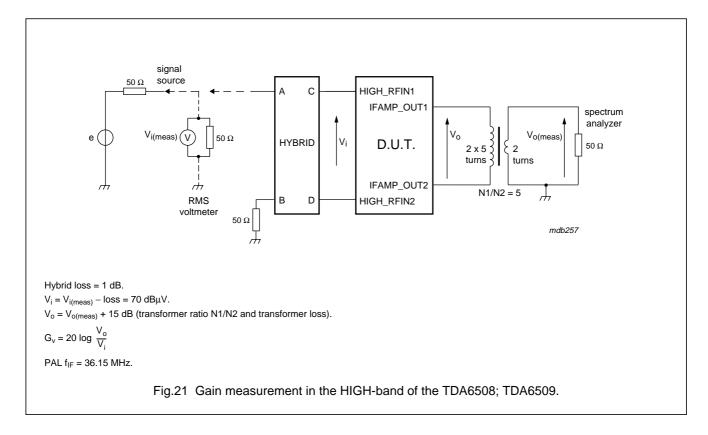




### 3-band mixer/oscillator and PLL for terrestrial tuners

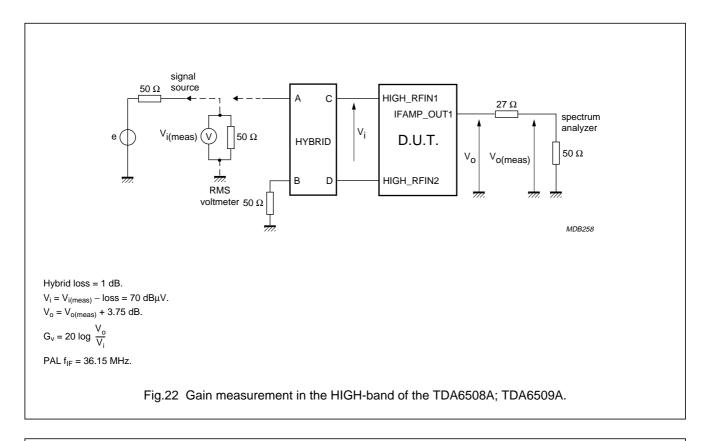
TDA6508; TDA6508A; TDA6509A

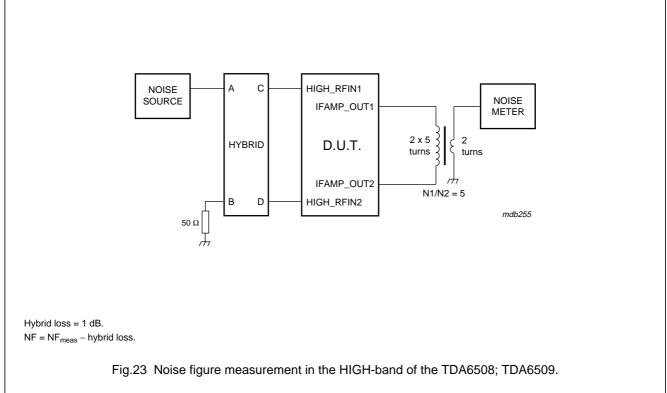




### 3-band mixer/oscillator and PLL for terrestrial tuners

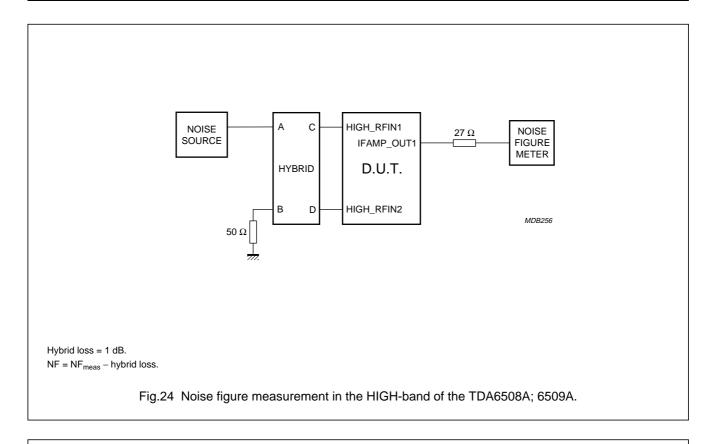
TDA6508; TDA6508A; TDA6509A

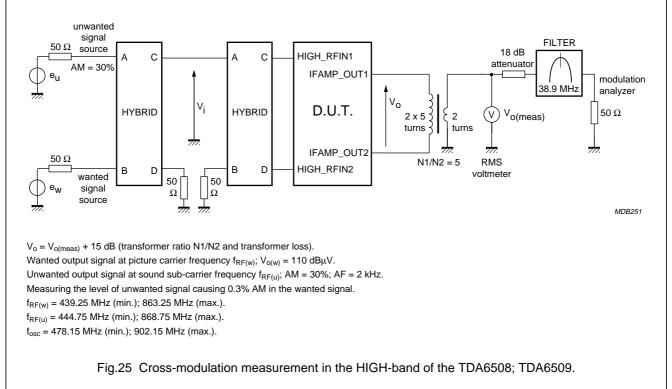




### 3-band mixer/oscillator and PLL for terrestrial tuners

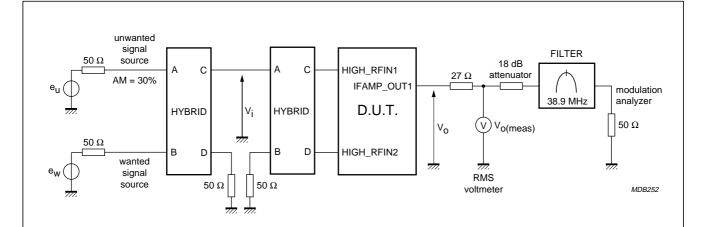
TDA6508; TDA6508A; TDA6509A





### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A



 $V_0 = V_{o(meas)} + 3.75 \text{ dB}.$ 

Wanted output signal at picture carrier frequency  $f_{RF(w)}$ ;  $V_{o(w)}$  = 100 dB $\mu$ V.

Unwanted output signal at sound sub-carrier frequency  $f_{RF(u)}$ ; AM = 30%; AF = 2 kHz.

We measure the level of unwanted signal causing 0.3% AM modulation in the wanted signal

 $f_{RF(w)}$  = 439.25 MHz (min.); 863.25 MHz (max.).

 $f_{RF(u)} = 444.75 \text{ MHz (min.)}; 868.75 \text{ MHz (max.)}.$ 

 $f_{osc} = 478.15 \text{ MHz (min.)}; 902.15 \text{ MHz (max.)}.$ 

Fig.26 Cross-modulation measurement in the HIGH-band of the TDA6508A; TDA6509A.

LOW RFIN

J3 (H=

C15 4.7 nF

R16 R13 1 kΩ 1 kΩ

D5 D2 D3

MID RFIN1

HIGH RFIN2

J7 J5

C12 1

C21

C22

18 pF

C13

**≠** 4.7 nF

MID RFIN2

C27

\_\_\_\_\_C29 \_\_\_\_\_100 pF

£ L1

R14 R15 1 kΩ 1 kΩ

**≠**4.7 nF

CTEST

C28 100 pF

± 62. ± 4.7 nF

J4 (

Philips Semiconductors

3-band mixer/oscillator and

PL

δ

TDA6508;

TDA6508A;

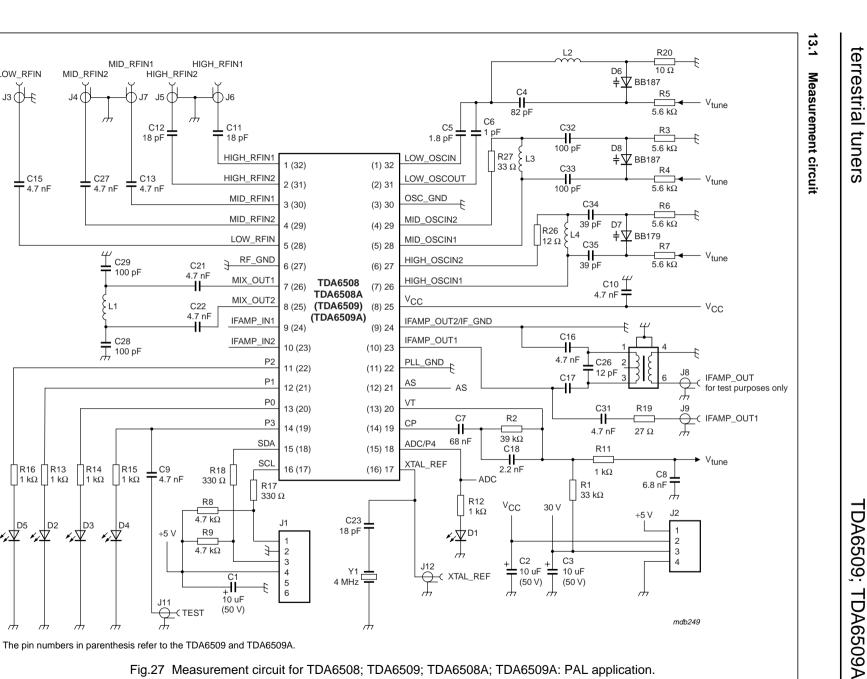


Fig.27 Measurement circuit for TDA6508; TDA6509; TDA6508A; TDA6509A: PAL application.

# 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

### 14 INTERNAL PIN CONFIGURATION

OVMDOL	Р	IN	DECODIBEION(1)	AVERAGE DC VOLTAGE (V)			
SYMBOL	TDA6508	TDA6509	DESCRIPTION <sup>(1)</sup>	LOW	MID	HIGH	
HIGH_RFIN1, HIGH_RFIN2	1, 2	32, 31	(32) (31) MDB228	_	-	1.0	
MID_RFIN1, MID_RFIN2	3, 4	30, 29	(30) (29) MDB229	_	1.0	-	
LOW_RFIN	5	28	(28) MDB230	1.8	-	-	
RF_GND	6	27	(27) MDB231	-	-	-	
MIX_OUT1, MIX_OUT2	7, 8	26, 25	(26) 8 (25) MDB232	2.9	2.9	2.9	

# 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

OVALDOL	Р	IN	DECODIDE ON (4)	AVERAGE DC VOLTAGE (V)			
SYMBOL	TDA6508	TDA6509	DESCRIPTION <sup>(1)</sup>	LOW	MID	HIGH	
IFAMP_IN1, IFAMP_IN2	9, 10	24, 23	9 (24) (10) (23) MDB241	3.0	3.0	3.0	
P0, P1, P2, P3	13, 12, 11, 14	20, 21, 22, 19	11 (22) (3) (4) (19) MDB242	high-Z or V <sub>CC</sub> – V <sub>DS</sub>	high-Z or V <sub>CC</sub> – V <sub>DS</sub>	high-Z or V <sub>CC</sub> – V <sub>DS</sub>	
SDA	15	18	(15) (18) MDB244	high-Z	high-Z	high-Z	
SCL	16	17	16 (17) MDB243	high-Z	high-Z	high-Z	
XTAL_REF	17	16	17) (16) MDB245	1.6	1.6	1.6	

# 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

CVMDOL	Р	IN	DESCRIPTION <sup>(1)</sup>	AVERA	GE DC VOLT	TAGE (V)
SYMBOL	TDA6508	TDA6509	DESCRIPTION	LOW	MID	HIGH
ADC/P4	18	15	18 (15) MDB246	high-Z or V <sub>CC</sub> – V <sub>DS</sub>	high-Z or V <sub>CC</sub> – V <sub>DS</sub>	high-Z or V <sub>CC</sub> – V <sub>DS</sub>
СР	19	14	(14) MDB247	1.0	1.0	1.0
VT	20	13	(13) MDB248	V <sub>VT</sub>	VvT	V <sub>VT</sub>
AS	21	12	(12) MDB236	1.25	1.25	1.25
PLL_GND	22	11	(22) (11) MDB237	0	0	0

# 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

SYMBOL	PIN		DESCRIPTION <sup>(1)</sup>	AVERAGE DC VOLTAGE (V)			
STWIBOL	TDA6508	TDA6509	DESCRIPTION	LOW	MID	HIGH	
IFAMP_OUT1, IFAMP_OUT2	23, 24	10, 9	(10) (9) MDB233	2.0	2.0	2.0	
IF_GND	24	9	(24) (9) MDB238	0	0	0	
V <sub>CC</sub>	25	8	supply voltage	5	5	5	
HIGH_OSCIN1	26, 27	7, 6	26 (7) (6) MDB239	2.3	2.3	1.3	

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

CVMDOL	PIN		DESCRIPTION <sup>(1)</sup>	AVERAGE DC VOLTAGE (V)				
SYMBOL	TDA6508	TDA6509	DESCRIPTION	LOW	MID	HIGH		
MID_OSCIN1	28, 29	5, 4	28 (5) (4) MDB240	2.3	1.3	2.3		
OSC_GND	30	3	(30) (3) MDB234	0	0	0		
LOW_OSCOUT, LOW_OSCIN	31, 32	2, 1	32 (1) MDB235	1.7, 2.9	1.4, 3.5	1.4, 3.5		

#### Note

1. The pin numbers in parenthesis apply to the TDA6508TT.

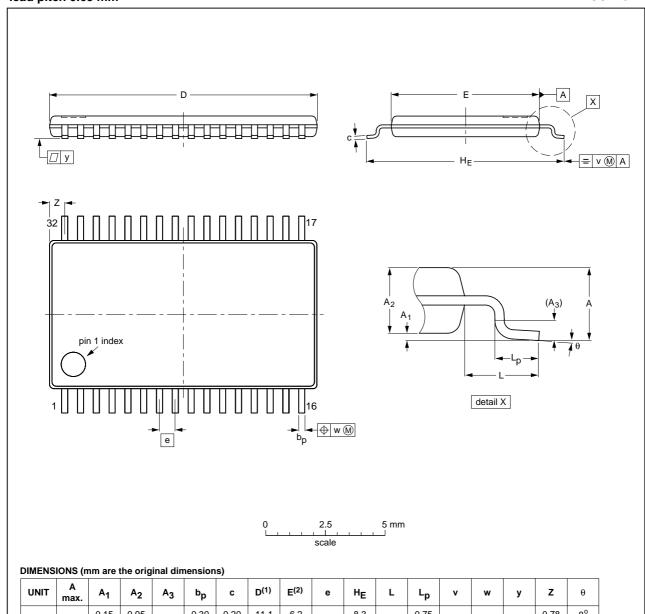
### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509; TDA6509A

#### 15 PACKAGE OUTLINES

TSSOP32: plastic thin shrink small outline package; 32 leads; body width 6.1 mm; lead pitch 0.65 mm

SOT487-1



UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(2)</sup>	е	HE	L	Lp	v	w	у	z	θ
mm	1.1	0.15 0.05	0.95 0.85	0.25	0.30 0.19	0.20 0.09	11.1 10.9	6.2 6.0	0.65	8.3 7.9	1	0.75 0.50	0.2	0.1	0.1	0.78 0.48	8° 0°

#### Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	1330E DATE
SOT487-1		MO-153				<del>99-12-27</del> 03-02-18

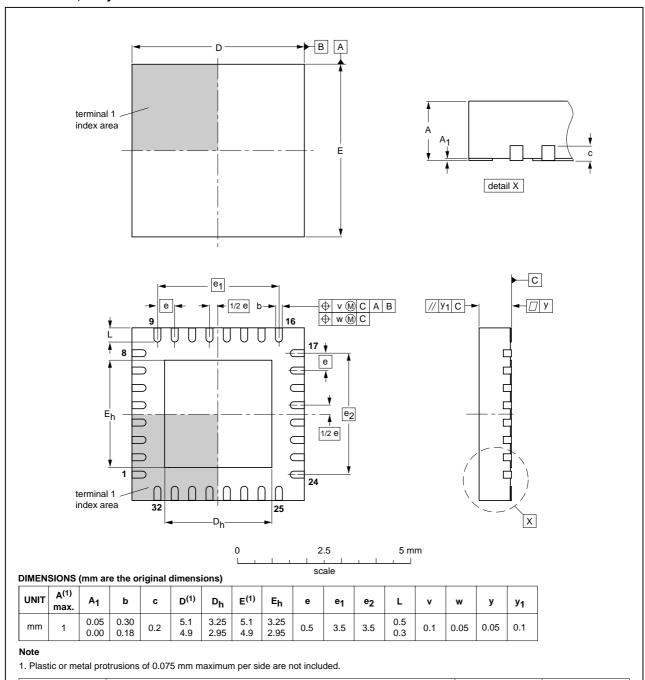
2005 Mar 25 37

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm

SOT617-1



OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	1350E DATE	
SOT617-1		MO-220			<del>-01-08-08</del> 02-10-18	

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

#### 16 SOLDERING

### 16.1 Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "Data Handbook IC26; Integrated Circuit Packages" (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

#### 16.2 Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement. Driven by legislation and environmental forces the worldwide use of lead-free solder pastes is increasing.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 seconds and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 °C to 270 °C depending on solder paste material. The top-surface temperature of the packages should preferably be kept:

- below 225 °C (SnPb process) or below 245 °C (Pb-free process)
  - for all BGA, HTSSON..T and SSOP..T packages
  - for packages with a thickness ≥ 2.5 mm
  - for packages with a thickness < 2.5 mm and a volume ≥ 350 mm<sup>3</sup> so called thick/large packages.
- below 240 °C (SnPb process) or below 260 °C (Pb-free process) for packages with a thickness < 2.5 mm and a volume < 350 mm<sup>3</sup> so called small/thin packages.

Moisture sensitivity precautions, as indicated on packing, must be respected at all times.

#### 16.3 Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems. To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
  - smaller than 1.27 mm, the footprint longitudinal axis must be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

 For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time of the leads in the wave ranges from 3 seconds to 4 seconds at 250 °C or 265 °C, depending on solder material applied, SnPb or Pb-free respectively.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

#### 16.4 Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to  $300\ ^{\circ}$ C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 seconds to 5 seconds between 270  $^{\circ}$ C and 320  $^{\circ}$ C.

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

#### 16.5 Suitability of surface mount IC packages for wave and reflow soldering methods

PACKAGE <sup>(1)</sup>	SOLDERING METHOD			
PACKAGE	WAVE	REFLOW <sup>(2)</sup>		
BGA, HTSSONT <sup>(3)</sup> , LBGA, LFBGA, SQFP, SSOPT <sup>(3)</sup> , TFBGA, VFBGA, XSON	not suitable	suitable		
DHVQFN, HBCC, HBGA, HLQFP, HSO, HSOP, HSQFP, HSSON, HTQFP, HTSSOP, HVQFN, HVSON, SMS	not suitable <sup>(4)</sup>	suitable		
PLCC <sup>(5)</sup> , SO, SOJ	suitable	suitable		
LQFP, QFP, TQFP	not recommended <sup>(5)(6)</sup>	suitable		
SSOP, TSSOP, VSO, VSSOP	not recommended <sup>(7)</sup>	suitable		
CWQCCNL <sup>(8)</sup> , PMFP <sup>(9)</sup> , WQCCNL <sup>(8)</sup>	not suitable	not suitable		

#### **Notes**

- 1. For more detailed information on the BGA packages refer to the "(LF)BGA Application Note" (AN01026); order a copy from your Philips Semiconductors sales office.
- 2. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the "Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods".
- 3. These transparent plastic packages are extremely sensitive to reflow soldering conditions and must on no account be processed through more than one soldering cycle or subjected to infrared reflow soldering with peak temperature exceeding 217  $^{\circ}$ C  $\pm$  10  $^{\circ}$ C measured in the atmosphere of the reflow oven. The package body peak temperature must be kept as low as possible.
- 4. These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.
- 5. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
- 6. Wave soldering is suitable for LQFP, QFP and TQFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
- 7. Wave soldering is suitable for SSOP, TSSOP, VSO and VSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.
- 8. Image sensor packages in principle should not be soldered. They are mounted in sockets or delivered pre-mounted on flex foil. However, the image sensor package can be mounted by the client on a flex foil by using a hot bar soldering process. The appropriate soldering profile can be provided on request.
- 9. Hot bar soldering or manual soldering is suitable for PMFP packages.

### 3-band mixer/oscillator and PLL for terrestrial tuners

TDA6508; TDA6508A; TDA6509A

#### 17 DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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